

Datasheet

Magnetic Sensor IC

North Unipolar Detection High Performance Low Power Hall-Effect Sensor IC



AS1811

General Description

Using low power CMOS process, the AS1811 is designed for low power, high performance unipolar detection hall-effect application, such as cover switch, contactless switch, solid state switch and lid close sensor etc battery operation. The hall IC integrated an on-chip hall voltage generator for magnetic sensing, a comparator that amplifiers the hall voltage, a Chopper amplifier, a Schmitt trigger to provide switching hysteresis for noise rejection, and a complementary output.

The total power consumption of AS1811 is typically less than 2uA at 1.8V power supply. AS1811 is designed to respond to alternating North pole. When the magnetic flux density (B) is larger than operate point (B_{OPN}), the output will be turned on (low), the output is held until the magnetic flux density (B) is lower than release point (B_{RPN}), then turn off (high).

The device is available in SOT553 DFN1216-4L and TSOT23-3L Package and is rated over the -40°C to 85°C. The package is RoHS and Green compliant.

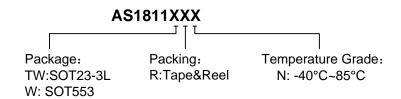
Features

- Input Voltage Range: 1.65V to 3.65V
- Micro-power consumption ideal for battery power applications
- Uniplar Operation, easy to use as output
- Very high sensitivity hall sensor
- Low Power CMOS process technology
- Chopper stabilization amplifier stage
- Magnetic Sensitivity (typical) B_{OPN}=-30Gauss, B_{RPN}=-23Gauss
- Good RF noise immunity
- No need pull-up resistor
- Small Solution Size
- RoHS & Green Compliant
- Small SOT553 DFN1216-4L and TSOT23-3L Package
- -40°C to +85 °C Temperature Range

Applications

- Cover switch in clam-shell cellular phones
- Cover switch in Notebook, PC/PAD
- Contact-less switch in consumer products
- Solid State Switch
- Handheld Wireless Handset Awake Switch
- Lid close sensor for battery-powered devise
- Magnet proximity sensor for reed switch replacement in low duty cycle applications
- DV, DSC, and White Goods

Ordering Information

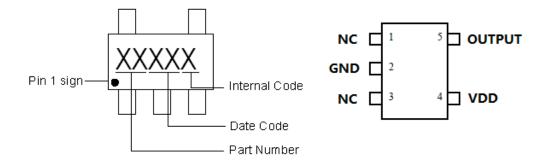


Part Number	B _{OPN} (Gauss)	B _{RPN} Gauss)	Package Type	Package Qty	Temperature	Eco Plan	Lead
AS1811WRN	-30	-23	SOT553	7-in reel 3000pcs/reel	-40∼85℃	Green	Cu
AS1811TWRN	-30	-23	TSOT23-3L	7-in reel 3000pcs/reel	-40∼85℃	Green	Cu
AS1811D4RN	-30	-23	DFN1216-4L	7-in reel 3000pcs/reel	-40∼85℃	Green	Cu



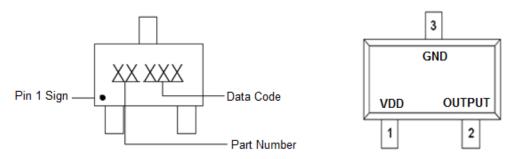
■ Marking & Pin Assignment

SOT553:



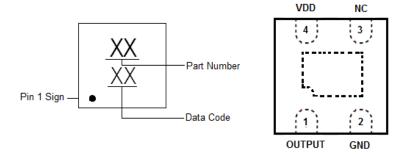
Pin Name	Pin No.	I/O	Pin Function	
Fili Naille	SOT553	1/0		
VDD	4	Р	Input Power Supply	
GND	2	Р	Ground	
NC	1, 3	-	Not Connected	
OUTPUT	5	0	Output Pin	

TSOT23-3L



Pin Name	Pin No. TSOT23-3L	I/O	Pin Function	
VDD	1	Р	Input Power Supply	
GND	3	Р	Ground	
OUTPUT	2	0	Output Pin	

DFN1216-4L

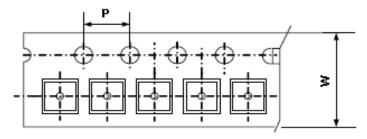


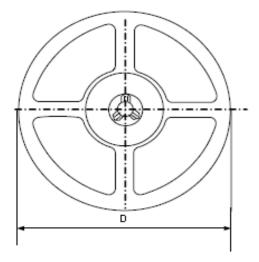
Pin Name	Pin No.	I/O	Pin Function	
Fill Name	DFN1216-4L	1/0		
VDD	4	Р	Input Power Supply	
GND	2	Р	Ground	
NC	3	-	Not Connected	
OUTPUT	1	0	Output Pin	

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■ Packing Information





Package Type	Carrier Width(W)	Pitch(P)	Reel Size(D)	Packing Minimum	
SOT553	8.0±0.1 mm	4.0±0.1 mm	180±1 mm	3000pcs	
TSOT23-3L	8.0±0.1 mm	4.0±0.1 mm	180±1 mm	3000pcs	
DFN1216-4L	8.0±0.1 mm	4.0±0.1 mm	180±1 mm	3000pcs	

Note: Carrier Tape Dimension, Reel Size and Packing Minimum